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*AN-329 Implementing an 8-Bit Buffer in COPS*



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# Implementing an 8-Bit Buffer in COPS™

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 Application Note 329  
 David Pointer  
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Implementing an 8-Bit Buffer in COPS

Sometimes a COP microcontroller must input and/or output 8-bit data; for instance, when handling ASCII data. In some applications, the processor must also provide temporary storage for 8-bit data before it is output. The COP instruction set and RAM structure lend themselves very nicely to providing a 32 digit, 8-bit buffer for a solution to these applications.

Such a large buffer is possible using a COP440 or a COP444L. The other members of the COP400 family with half as much RAM as these two would provide a 16 digit 8-bit buffer using the techniques described in this example.

Four adjacent RAM registers (16 digits each) are required. Referring to *Figure 1*, registers 4, 5, 6, and 7 are used for the buffer. Each RAM location contains 4 bits, so 2 locations will be used to store a byte of data. But these RAM locations are not adjacent to each other. You will note that the MSD of digit number 0A hex is in RAM location (4, A) while the LSD of the same digit is in RAM location (6, A).

The 2 RAM locations CHARM and CHARL are used for temporary storage of an 8-bit value.

In addition, 4 RAM locations are used for buffer pointers: those labelled IPM and IPL are the MSD and LSD of the

input pointer, and those labelled OPM and OPL are the MSD and LSD of the output pointer. Each pointer's function is to store an 8-bit counter whose value ranges from 00 hex thru 1F hex. The input pointer's value is used for storing the temporary storage buffer contents into the digit with the same number. For example, if the input pointer equals 14 hex, then the contents of CHARM would be stored in RAM location (5, 4) and the contents of CHARL would be stored in RAM location (7, 4). The output pointer's value is used for retrieving a digit from the buffer and putting it in CHARM and CHARL. For instance, if the output pointer equals 05 hex, then the contents of RAM location (4, 5) would be transferred to CHARM and the contents of RAM location (6, 5) would be transferred to CHARL.

A simple example of one possible application of the buffer is flowcharted in *Figure 2*. In this example, data is input to CHARM and CHARL, then stored in the buffer. An output device (a printer) is checked to see if it is ready to receive data. If it is, data is brought out of the buffer and put in CHARM and CHARL for output to the printer.

Pages 3 and 4 contain a listing of the subroutines needed to perform the data transfers in the 32-digit, 8-bit buffer.

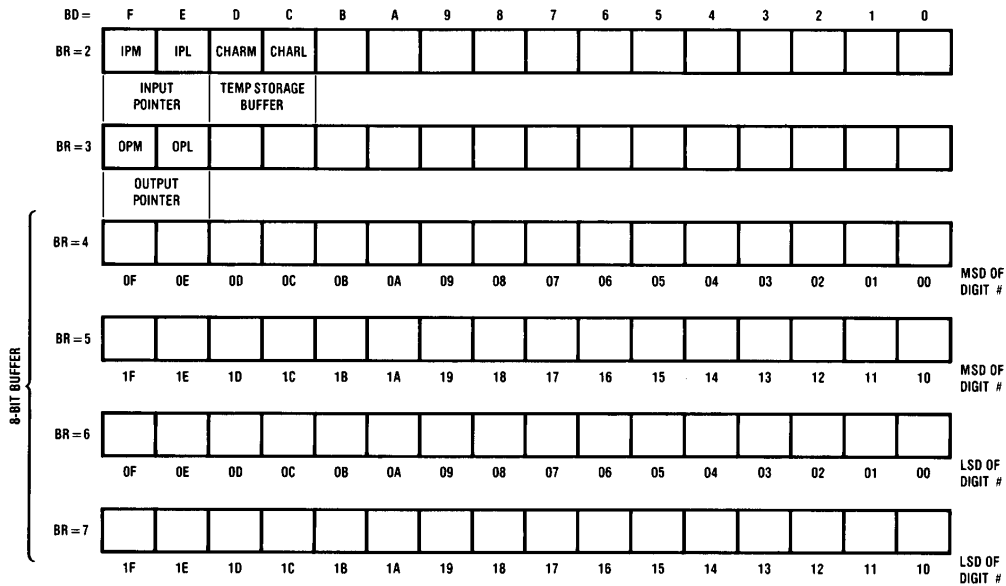


FIGURE 1. 8-Bit Buffer RAM Map

TL/DD/5181-1

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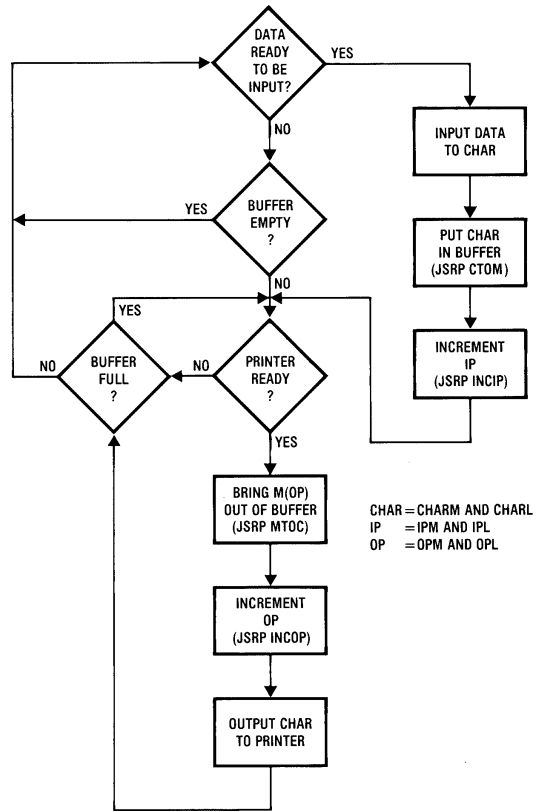


FIGURE 2. Buffer Example Flowchart

TL/DD/5181-2

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1          ;*****
2          ;***          ***
3          ;*** 8-BIT RAM BUFFER SUBROUTINES ***
4          ;***          ***
5          ;*****
6          ;THESE ARE SUBROUTINES FOR IMPLEMENTING A 32 BYTE
7          ;BUFFER IN A COP440 OR COP444L RAM 9/3/82
8  01BC    .CHIP 444
9          .TITLE BUFFER
10 002D    CHARM =      2,13          ;TEMPORARY STORAGE BUFFER MSD
11 002C    CHARL =      2,12          ;TEMPORARY STORAGE BUFFER LSD
12 002F    IPM =       2,15          ;INPUT POINTER MSD
13 002E    IPL =       2,14          ;INPUT POINTER LSD
14 003F    OPM =       3,15          ;OUTPUT POINTER MSD
15 003E    OPL =       3,14          ;OUTPUT POINTER LSD
16 000 00          CLRA
17 0080    .PAGE 2
18          ;MTOC IS A SUBROUTINE THAT TRANSFERS M(OPM) AND M(OPL) TO
19          ;CHARM AND CHARL
20 080 233E    MTOC:  LDD    OPL          ;LOAD LSD OUTPUT POINTER
21 082 50          CAB          ;WHICH IS BD
22 083 233F    LDD    OPM          ;LOAD MSB OUTPUT POINTER FOR B
23 085 54          AISC  4          ;MAKE BR EQUAL 4 OR 5
24 086 12          XABR
25 087 25          LD     2          ;LOAD M(OPM), MAKE BR = 6 OR 7
26 088 23AD    XAD    CHARM        ;M(OPM) TO CHARM
27 08A 05          LD     M(OPL)    ;LOAD M(OPL)
28 08B 23AC    XAD    CHARL        ;M(OPL) TO CHARL
29 08D 48          RET
30          ;
31          ;
32          ;CTOM IS A SUBROUTINE THAT TRANSFERS CHARM AND CHARL TO
33          ;M(IPM) AND M(IPL)
34 08E 232E    CTOM:  LDD    IPL          ;LOAD LSD INPUT POINTER
35 090 50          CAB          ;WHICH IS BD
36 091 232F    LDD    IPM          ;LOAD MSD INPUT POINTER FOR BR
37 093 54          AISC  4          ;MAKE BR = 4 OR 5
38 094 12          XABR
39 095 232D    LDD    CHARM        ;LOAD MSD TEMP STORAGE
40 097 26          X     2          ;TO M(OPM), MAKE BR = 6 OR 7
41 098 232C    LDD    CHARL        ;LOAD LSD TEMP STORAGE
42 09A 06          X     M(OPL)    ;TO M(OPL)
43 09B 48          RET
44          ;
45          ;

```

COP CROSS ASSEMBLER PAGE: 2  
BUFFER

```

46      .FORM
47      ;INCREMENTS INPUT POINT OR OUTPUT POINTER, ROLLS OVER
48      ;AT 1F HEX
49 09C 2D  INCIP: LBI   IPL           ;POINT TO LSD OF POINTER
50 09D 3D  INCOP: LBI   OPL           ;C=1 FOR INCREMENT
51 09E 22      SC           ;C=1 FOR INCREMENT
52 09F 00      CLRA
53 0A0 30      ASC           ;INCREMENT RAM VALUE
54 0A1 44      NOP           ;NEGATES SKIP CONDITION
55 0A2 04      XIS           ;STORE AND POINT TO (X,F)
56 0A3 00      CLRA
57 0A4 30      ASC           ;PROPAGATE CARRY, IF ANY, TO MS
58 0A5 44      NOP
59 0A6 06      X           ;STORE
60 0A7 45      RMB   1       ;ROLL OVER AT X'1F
61 0A8 48      RET
62      ;
63      ;
64      .END
    
```

COP CROSS ASSEMBLER PAGE: 3  
BUFFER

```

CHARL 002C  CHARM 002D  CTOM  008E *  INCIP  009C *
INCOP  009D *  IPL   002E  IPM   002F  MTOC  0080 *
OPL   003E  OPM   003F
NO ERROR LINES
42 ROM WORDS USED
COP 444 ASSEMBLY
SOURCE CHECKSUM = C6A5
INPUT FILE 6:RBUFFC.SRC VN: 5
    
```

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Fax: 1(800) 737-7018

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Fax: (+49) 0-180-530 85 86  
Email: cnjwge@tevm2.nsc.com  
Deutsch Tel: (+49) 0-180-530 85 85  
English Tel: (+49) 0-180-532 78 32  
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**National Semiconductor Hong Kong Ltd.**  
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